Silicon PIN Photodiode

FEATURES

- Package type: surface-mount
- Package form: top view
- Dimensions (L x W x H in mm): 4.8 x 2.5 x 0.48
- Radiant sensitive area (in mm^2): 4.5
- 0.48 mm low profile package
- Enhanced sensitivity for visible light
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 65°$
- Floor life: 168 h, MSL 3, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free

e4

RoHS COMPLIANT

HALOGEN FREE GREEN (5-2008)

DESCRIPTION

VEMD8080 is a high speed and high sensitive PIN photodiode with enhanced sensitivity for visible light. It is a low profile surface-mount device (SMD) including the chip with a 4.5 mm^2 sensitive area detecting visible and near infrared radiation.

APPLICATIONS

- High speed photo detector
- Wearables

PRODUCT SUMMARY			
COMPONENT	**I_{ra} (µA)**	**φ (deg)**	**$\lambda_{0.1}$ (nm)**
VEMD8080	28	± 65	350 to 1100

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION			
ORDERING CODE	**PACKAGING**	**REMARKS**	**PACKAGE FORM**
VEMD8080	Tape and reel	MOQ: 5000 pcs, 5000 pcs/reel	Top view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	20	V
Junction temperature		T_j	85	°C
Operating temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +85	°C
Soldering temperature	According to reflow solder profile Fig. 8	T_{sd}	260	°C
Thermal resistance junction-to-ambient		R_{thJA}	350	K/W
ESD safety HBM	± 2000 V, 1.5 kΩ, 100 pF, 3 pulses	ESD_{HBM}	≥ 2	kV

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 50 mA	V_F	-	1.2	1.6	V
Breakdown voltage	I_R = 100 µA, E = 0	$V_{(BR)}$	20	-	-	V
Reverse dark current	V_R = 10 V, E = 0	I_{ro}	-	0.2	10	nA
Diode capacitance	V_R = 0 V, f = 1 MHz, E = 0	C_D	-	47	-	pF
	V_R = 3 V, f = 1 MHz, E = 0	C_D	-	17	40	pF
Open circuit voltage	E_e = 1 mW/cm², λ = 950 nm	V_o	-	320	-	mV
Temperature coefficient of V_o	E_e = 1 mW/cm², λ = 950 nm	TK_{Vo}	-	-3.0	-	mV/K
Short circuit current	E_e = 1 mW/cm², λ = 950 nm	I_k	-	32	-	µA
Temperature coefficient of I_k	E_e = 1 mW/cm², λ = 950 nm	TK_{Ik}	-	0.1	-	%/K
Reverse light current	E_e = 1 mW/cm², λ = 850 nm, V_R = 5 V	I_{ra}	23	28	33	µA
	E_e = 0.25 mW/cm², λ = 525 nm, V_R = 5 V	I_{ra}	3.4	4.4	5.3	µA
Angle of half sensitivity		φ	-	± 65	-	deg
Wavelength of peak sensitivity		λ_p	-	850	-	nm
Range of spectral bandwidth		$\lambda_{0.1}$	-	350 to 1100	-	nm
Rise time	V_R = 10 V, R_L = 1 kΩ, λ = 830 nm	t_r	-	70	-	ns
Fall time	V_R = 10 V, R_L = 1 kΩ, λ = 830 nm	t_f	-	70	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

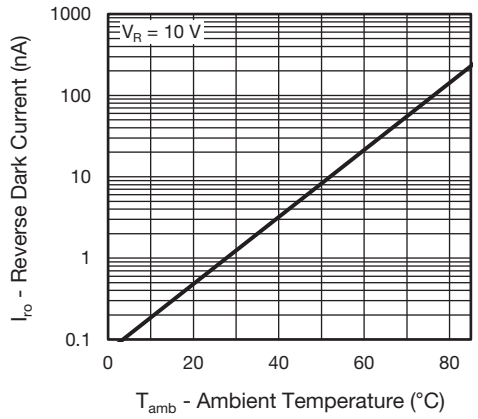


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

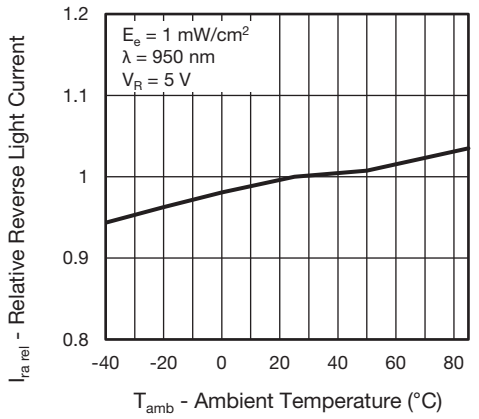


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature

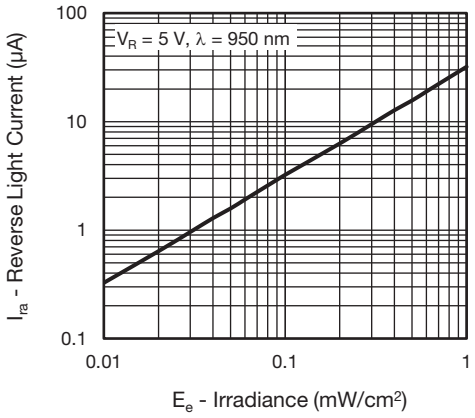


Fig. 3 - Reverse Light Current vs. Irradiance

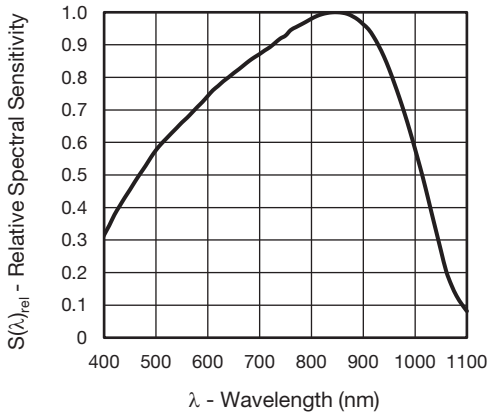


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

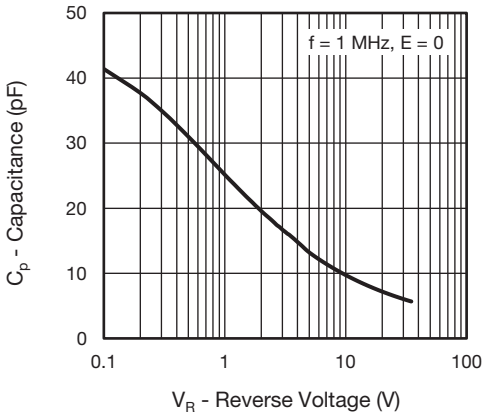


Fig. 4 - Diode Capacitance vs. Reverse Voltage

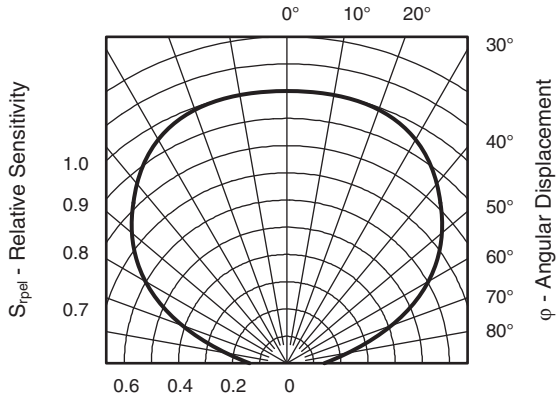
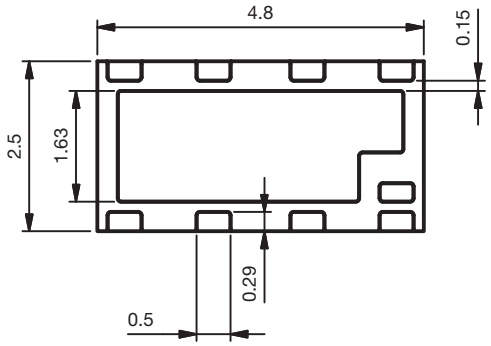
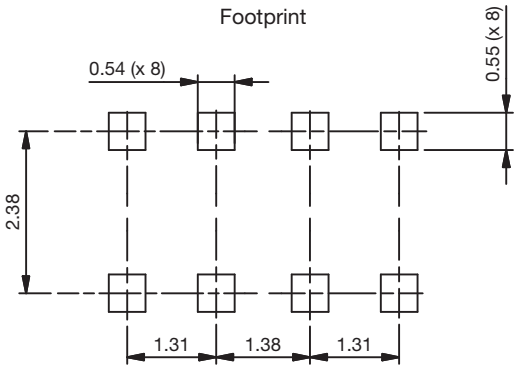
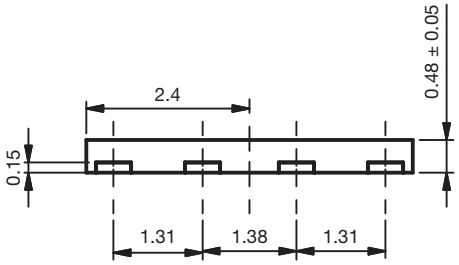


Fig. 6 - Relative Sensitivity vs. Angular Displacement

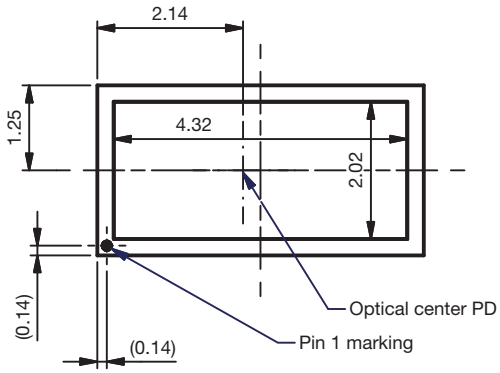
PACKAGE DIMENSIONS in millimeters



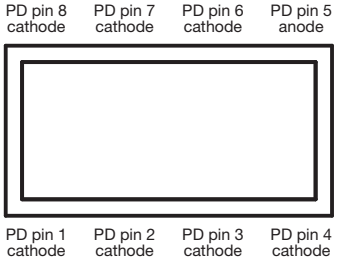




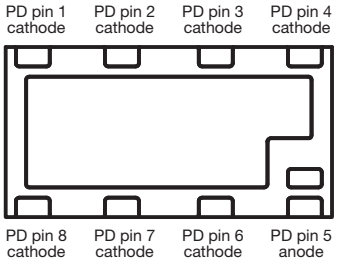
Not indicated tolerances ± 0.1 mm

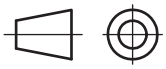


Pinning top view



Pinning bottom view



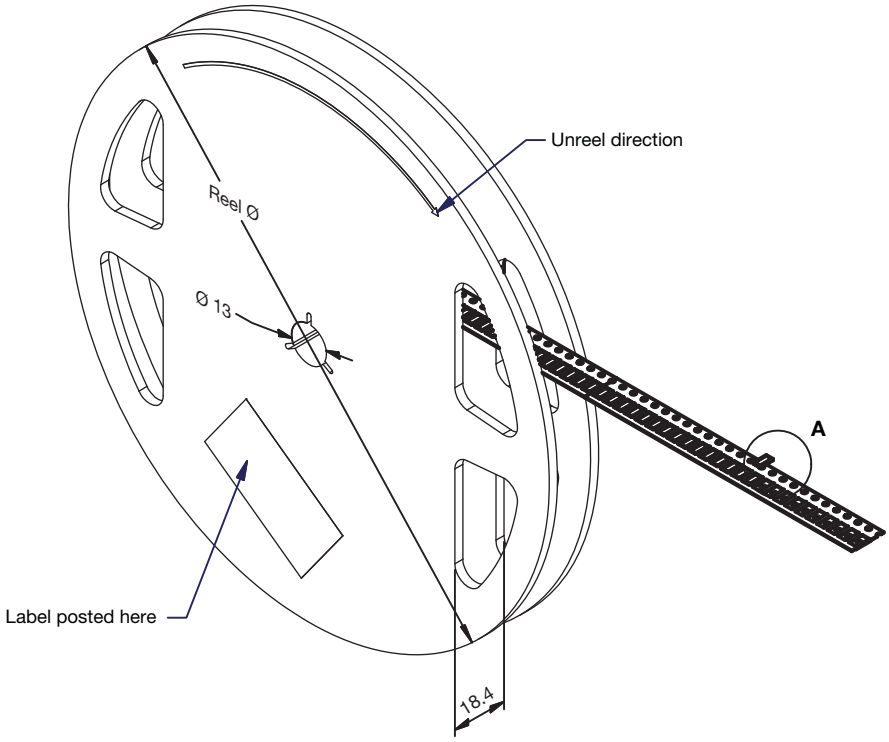


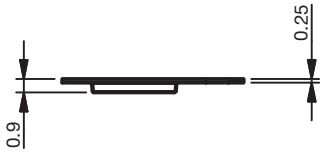
Technical drawings according to DIN specification.

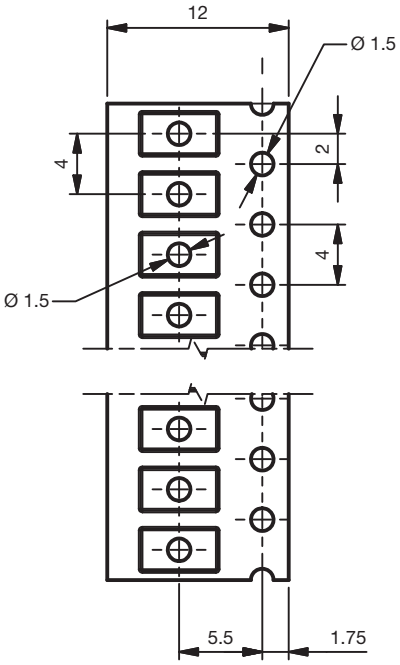
Drawing number: 6.550-5354.01-4
Issue: 1; 20.04.2018

TAPE AND REEL DIMENSIONS in millimeters

Non tolerated dimensions ± 0.1 mm
Reel design is representative for different types







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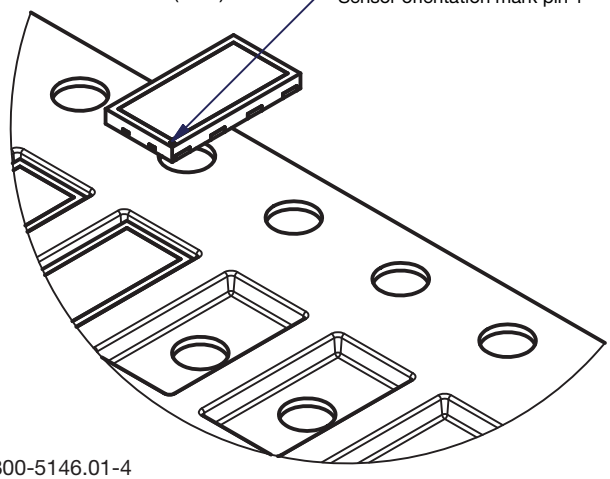

Drawing-No.: 9.800-5146.01-4
Issue: 1; 20.04.2018

SOLDER PROFILE

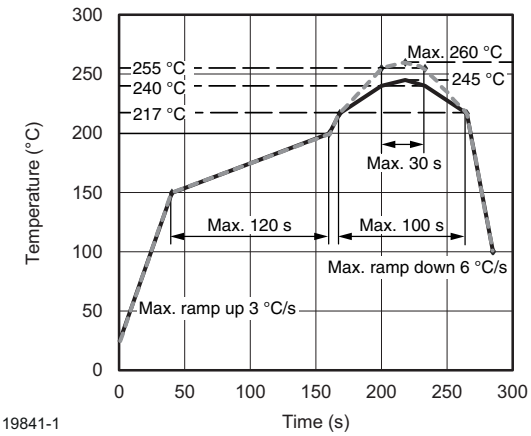

Fig. 7 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %
or
96 h at 60 °C (+ 5 °C), RH < 5 %

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